

December 2013

FPAB30BH60B

PFC SPM® 3 Series for Single-Phase Boost PFC

Features

- UL Certified No. E209204 (UL1557)
- 600 V 30 A Single-Phase Boost PFC with Integral Gate Driver and Protection
- Very Low Thermal Resistance Using Al₂O₃ DBC Substrate
- Full-Wave Bridge Rectifier and High-Performance Output Diode
- · Built-in NTC Thermistor for Temperature Monitoring
- Optimized for 20kHz Switching Frequency
- Isolation Rating: 2500 Vrms/min.

Applications

• Single-Phase Boost PFC Converter

Related Source

- AN-9090 PFC SPM 3 Series User's Guide
- AN-9091 Boost PFC Inductor Design Guide

General Description

The FPAB30BH60B is an advanced PFC SPM® 3 module providing a fully-featured, high-performance Boost PFC (Power Factor Correction) input power stage for consumer, medical, and industrial applications. These single-phase modules integrate optimized gate drive of the built-in IGBT to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockout, over-current shutdown, thermal monitoring, and fault reporting. These modules also feature a full-wave rectifier, and high-performance output diode for additional space savings and mounting convenience.

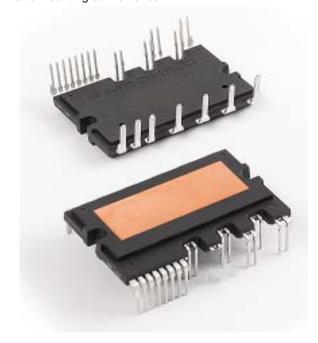


Figure 1. Package Overview

Package Marking & Ordering Information

Device	Device Marking	Package	Packing Type	Quantity	
FPAB30BH60B	FPAB30BH60B	SPMIC-027	Rail	10	

Integrated Power Functions

• PFC converter for single-phase AC / DC power conversion (please refer to Figure 3)

Integrated Drive, Protection, and System Control Functions

- For IGBTs: gate drive circuit, Over-Current Protection (OCP), control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- Fault signal: corresponding to OC and UV fault
- · Built-in thermistor: temperature monitoring
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

Pin Configuration

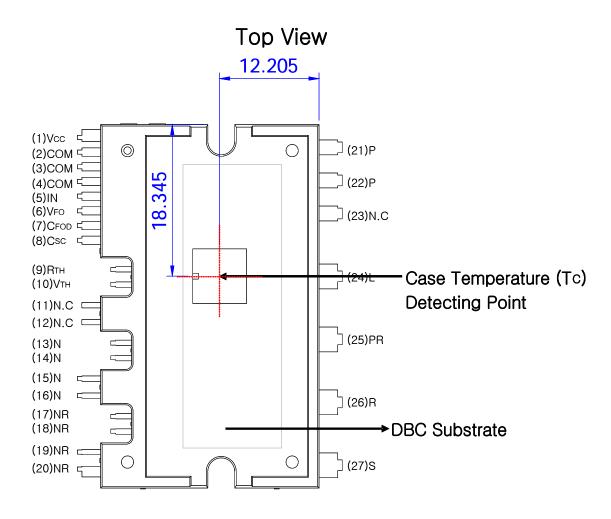


Figure 2. Top View

Notes :

1. For the measurement point of case temperature (T_C) , please refer to Figure 2.

Pin Descriptions

Pin Number	Pin Name	Pin Description
1	V _{CC}	Common Bias Voltage for IC and IGBT Driving
2,3,4	СОМ	Common Supply Ground
5	IN	Signal Input for IGBT
6	V_{FO}	Fault Output
7	C_{FOD}	Capacitor for Fault Output Duration Selection
8	C _{SC}	Capacitor (Low-Pass Filter) for Over-Current Detection
9	R _(TH)	Series Resistor for The Use of Thermistor
10	V _(TH)	Thermistor Bias Voltage
11,12	N.C	No Connection*
13~16	N	IGBT Emitter
17~20	N _R	Negative DC-Link of Rectifier
21,22	Р	Positive Rail of DC-Link
23	N.C	No Connection
24	L	Reactor Connection Pin
25	P _R	Positive DC-Link of Rectifier
26	R	AC Input for R-Phase
27	S	AC Input for S-Phase

^{* 11}th and 12th pins are cut. Please refer to package outline drawings for more detail.

Internal Equivalent Circuit and Input/Output Pins

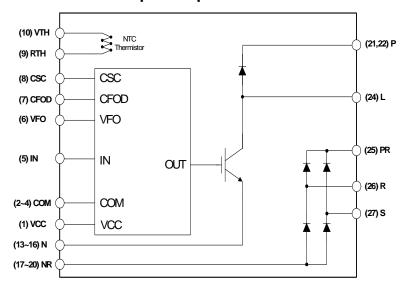


Figure 3. Internal Block Diagram

Absolute Maximum Ratings ($T_J = 25$ °C, unless otherwise specified.)

Converter Part

Symbol	Item	Condition	Rating	Unit
V _i	Supply Voltage	Applied between R - S	264	V _{rms}
V _{i(Surge)}	Supply Voltage (Surge)	Applied between R - S	500	V
V _{PN}	Output Voltage	Applied between P - N	450	V
V _{PN(Surge)}	Output Voltage (Surge)	Applied between P - N	500	V
V _{CES}	Collector - Emitter Voltage		600	V
I _C	Each IGBT Collector Current	T _C = 25°C, T _J < 150°C	30	Α
I _{CP}	Each IGBT Collector Current (Peak)	$T_C = 25$ °C, $T_J < 150$ °C, Under 1ms Pulse Width	60	Α
P _C	Collector Dissipation	T _C = 25°C	104	W
V _{RRM}	Repititive Peak Reverse Voltage		600	V
I _{FSM}	Peak Forward Surge Current	Single Half Sine-Wave	350	Α
TJ	Operating Junction Temperature		-40 ~ 150	°C

Control Part

Symbol	Item	Condition	Rating	Unit
V _{CC}	Control Supply Voltage	Applied between V _{CC} - COM	20	V
V _{IN}	Input Signal Voltage	Applied between IN - COM	-0.3 ~ V _{CC} +0.3	V
V _{FO}	Fault Output Supply Voltage	Applied between V _{FO} - COM	-0.3 ~ V _{CC} +0.3	V
I _{FO}	Fault Output Current	Sink Current at V _{FO} Pin	5	mA
V _{SC}	Current Sensing Input Voltage	Applied between C _{SC} - COM	-0.3 ~ V _{CC} +0.3	V

Total System

Symbol	Item	Condition Rating		Unit
T _{STG}	Storage Temperature		-40 ~ 125	ပ္
V _{ISO}	9	60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat Sink Plate	2500	V _{rms}

Thermal Resistance

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
$R_{\theta(j-c)Q}$	Junction to Case Thermal Resistance	IGBT	-	-	1.2	°C/W
$R_{\theta(j-c)F}$		FRD	-	-	1.4	°C/W
$R_{\theta(j-c)R}$		Rectifier (per 1 / 4 module)	-	-	1.7	°C/W

Electrical Characteristics ($T_J = 25$ °C, unless otherwise specified.)

Converter Part

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V _{CE(SAT)}	IGBT Saturation Voltage	V _{CC} = 15 V, V _{IN} = 5 V, I _C = 30 A	-	2.2	2.8	V
V_{FF}	FRD Forward Voltage	I _F = 30 A	-	1.9	2.6	V
V_{FR}	Rectifier Forward Voltage	I _F = 30 A	-	1.2	1.5	V
t _{ON}	Switching Times	V _{PN} = 400 V, V _{CC} = 15V, I _C = 30 A	-	500	-	ns
t _{C(ON)}		$V_{IN} = 0 V \leftrightarrow 5 V$, Inductive Load	-	200	-	ns
t _{OFF}		(Note 2)	-	420	-	ns
t _{C(OFF)}			-	100	-	ns
t _{rr}			-	60	-	ns
I _{rr}			-	7	-	Α
I _{CES}	Collector - Emitter Leakage Current	$V_{CE} = V_{CES}$	-	-	250	μА

Notes:
2. toN and toFF include the propagation delay of the internal drive IC. to(ON) and to(OFF) are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

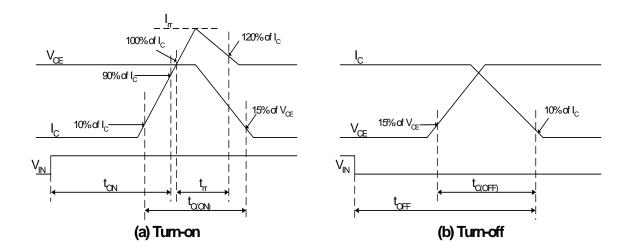


Figure 4. Switching Time Definition

Control Part

Symbol	Item	Condition		Min.	Тур.	Max.	Unit
I _{QCCL}	Quiescent V _{CC} Supply Current	V _{CC} = 15 V, IN = 0 V	V _{CC} - COM	ı	-	26	mA
V _{FOH}	Fault Output Voltage	V _{SC} = 0 V, V _{FO} Circu	it: 4.7 kΩ to 5 V Pull-up	4.5	-	-	V
V _{FOL}		V _{SC} = 1 V, V _{FO} Circu	it: 4.7 kΩ to 5 V Pull-up	1	-	0.8	V
V _{SC(ref)}	Over-Current Trip Level	V _{CC} = 15 V		0.45	0.50	0.55	V
UV _{CCD}	Supply Circuit Under-Voltage	Detection Level		10.7	11.9	13.0	V
UV _{CCR}	Protection	Reset Level		11.2	12.4	13.2	V
t _{FOD}	Fault-Out Pulse Width	C _{FOD} = 33 nF (Note 3)		1.4	1.8	2.0	ms
V _{IN(ON)}	ON Threshold Voltage	Applied between IN - COM		2.8	-	-	V
V _{IN(OFF)}	OFF Threshold Voltage			1	-	0.8	V
R _{TH}	Resistance of Thermistor	at T _{TH} = 25°C (Note 4, Figure 5)		1	47.0	-	kΩ
		at T _{TH} = 100°C (Note	4, Figure 5)	1	2.9	-	kΩ

Notes:3. The fault-out pulse width t_{FOD} depends on the capacitance value of C_{FOD} according to the following approximate equation: $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}$ [F].
4. T_{TH} is the temperature of know case temperature (T_C) , please make the experiment considering your application.

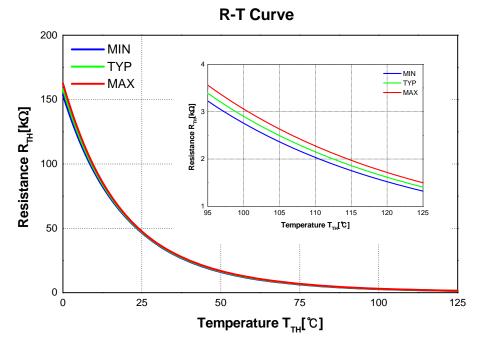


Figure 5. R-T Curve of the Built-In Thermistor

Recommended Operating Condition

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V _i	Input Supply Voltage	Applied between R - S	187	220	253	V_{rms}
V _{PN}	Output Voltage	Applied between P - N	-	380	400	V
V _{CC}	Control Supply Voltage	Applied between V _{CC(L)} - COM	13.5	15.0	16.5	V
dV _{CC} /dt	Control Supply Variation		-1	-	1	V/μs
f _{PWM}	PWM Input Frequency	T _J ≤ 150°C	-	20	-	kHz
l _i	Allowable Input Current	T_C < 90°C, V_i = 220 V, V_{PN} = 380 V V_{PWM} = 20 kHz	-	-	30	A _{peak}

Mechanical Characteristics and Ratings

Item	Co	ndition	Min.	Тур.	Max.	Unit
Mounting Torque	Mounting Screw: M3	Recommended 0.62 N•m	0.51	0.62	0.72	N•m
Device Flatness	See Figure 6		0	-	+120	μm
Weight			-	15.00	-	g

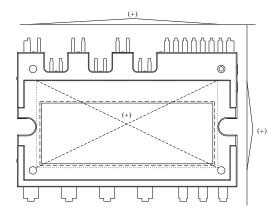
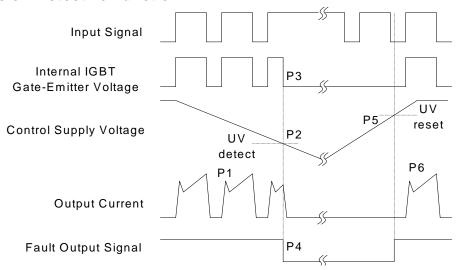


Figure 6. Flatness Measurement Position

Time Charts of Protective Function

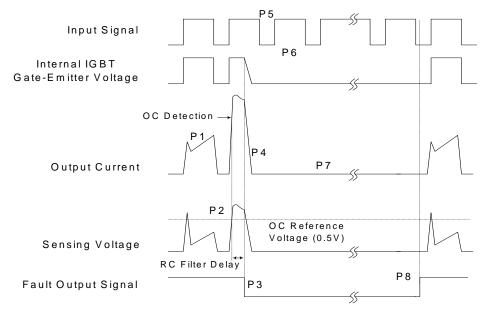


P1: Normal operation: IGBT ON and conducting current.

P2: Under-voltage detection. P3: IGBT gate interrupt. P4: Fault signal generation. P5: Under-voltage reset.

P6: Normal operation: IGBT ON and conducting current.

Figure 7. Under-Voltage Protection



P1: Normal operation: IGBT ON and conducting current.

P2: Over current detection.

P3: IGBT gate interrupt / fault signal generation.

P4: IGBT is slowly turned off.

P5: IGBT OFF signal.

P6: IGBT ON signa: but IGBT cannot be turned on during the fault output activation.

P7: IGBT OFF state.

P8 : Fault output reset and normal operation start.

Figure 8. Over-Current Protection

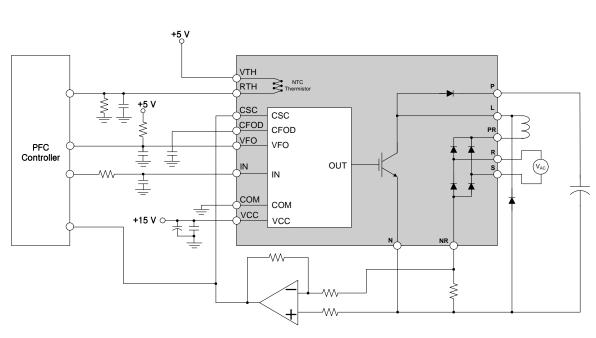
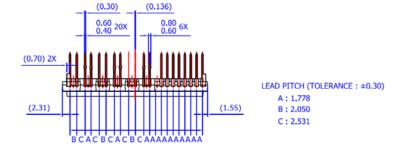


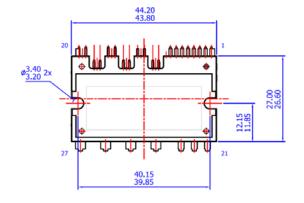
Figure 9. Application Example

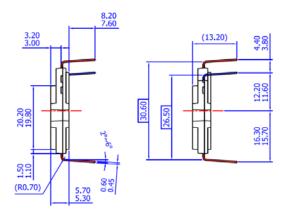
Notes:

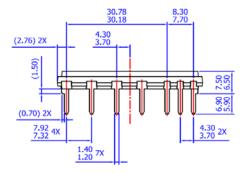
- 5. Each capacitors should be located as close to PFC SPM® product pins as possible. 6. It's recommended that anti-parallel diode should be connected with IGBT.

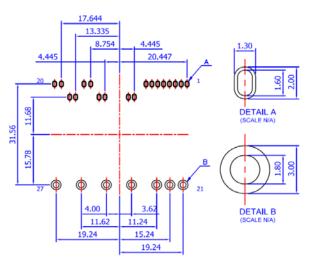
Detailed Package Outline Drawings











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